PCN Number:	20160607001		PCN Date:	06/17/2016
Title:	Datasheet for DS92LV2421/DS92LV2422			
Customer Contact:	PCN Manager		Dept:	Quality Services

Change Type:

☐ Assembly Site		☐ Design		☐ Wafer Bump Site	
☐ Assembly Process		☒ Data Sheet		☐ Wafer Bump Material	
☐ Assembly Materials		☐ Part number change		☐ Wafer Bump Process	
☐ Mechanical Specification		☐ Test Site		☐ Wafer Fab Site	
☐ Packing/Shipping/Labeling		☐ Test Process		☐ Wafer Fab Materials	
				☐ Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is updated as seen in the change revision history below:

TEXAS INSTRUMENTS

DS92LV2421, DS92LV2422

SNLS321C – MAY 2010 – REVISED MAY 2016

www.ti.com

Changes from Revision B (April 2013) to Revision C   Page

Device Family	Change From:	Change To:
DS92LV2421/DS92LV2422	SNLS321B	**SNLS321C**

These changes may be reviewed at the datasheet links provided.
http://www.ti.com/product/ds92lv2421

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
DS92LV2421SQ/NOPB	DS92LV2421SQX/NOPB	DS92LV2422SQE/NOPB	
DS92LV2421SQE/NOPB	DS92LV2422SQ/NOPB	DS92LV2422SQX/NOPB	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com